

Title (en)  
DECAY MOLD

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Application  
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Abstract (en)  
[origin: EP0374956A2] A decay mold comprising a powder material having a transition accompanied with a volume change occurring at a temperature lower than the sintering temperature and a binder thereof, comprising a material thermally decomposable at a temperature lower than the sintering temperature, or comprising a material soluble at least in one solvent in which the molding assistant to impart formability to the powder to be molded is insoluble. By using the mold of the invention, an arbitrary form of sintered products can be manufactured without damaging it at the demolding.

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IPC 8 full level  
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Citation (search report)  
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